

EPICLON[®] N-865

Modified Novolac type epoxy resin

General description

EPICLON[®] N-800 series are multi-functional epoxy resins derived from modified novolac, and designed for application of high performance epoxy molding compound (EMC) for semi-conductor, especially for surface mount devices (SMD). The most advantage of these products is high curability and high glass transition temperature compared with cresol novolac type (ECN). So N-800 series are suitable for electronics applications, EMC, PWB, Resist Ink and powder coatings.

Typical properties*

Appearance	Marble lock
Epoxy equivalent, g/eq	208
Softening point, °C	68
ICI viscosity, mPa.s	2.8
Hydrolyzable Cl content, wt ppm	80
Na ion, wt ppm	<1
Cl ion, wt ppm	<1

*Typical properties; not to be construed as specifications.

Evaluation formulation

	Parts by weight
EPICLON[®] N-865	66.7
Hardener: PHENOLITE [®] TD-2131 (Novolac type phenolic resin)	33.3
Accelerator: Triphenylphosphine	1.0

Curing schedule : 175°C x 5hrs.

Curability and Cured resin properties

Gelation time 175°C, sec	32
T _g by DMA, °C	198
Moisture Absorption, 85°C/85%RH 300hours, %	1.87
Coefficient of Thermal Expansion, ppm	55

Storage

EPICLON[®] N-865 has a shelf-life of at least 6 month if it is stored in a cool, dry area.